

CLAIMS

1. A thermosetting resin composition comprising:

- (1) a metal salt of a disubstituted phosphinic acid, and
 5 (2) a resin having a dielectric constant of 2.9 or less
 at a frequency of 1 GHz or more.

2. The thermosetting resin composition according to claim 1,
 wherein the dielectric constant of the thermosetting resin
 10 composition is 3.0 or less at a frequency of 1 GHz or more.

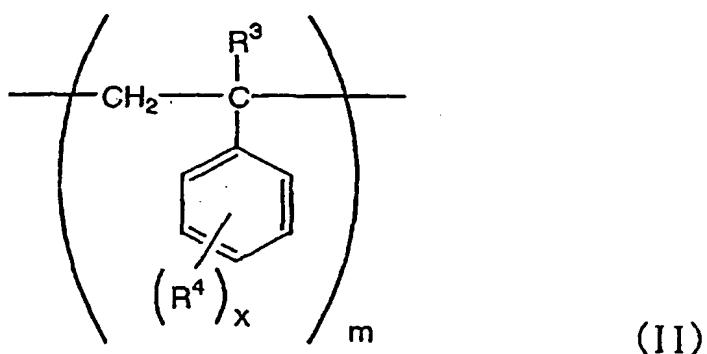
3. The thermosetting resin composition according to claim 1 or
 2, which further comprises (3) a thermosetting nitrogen
 atom-containing resin.

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4. The thermosetting resin composition according to any one of
 claims 1 to 3, wherein the component (2) is at least one resin
 compositions selected from the group consisting of:

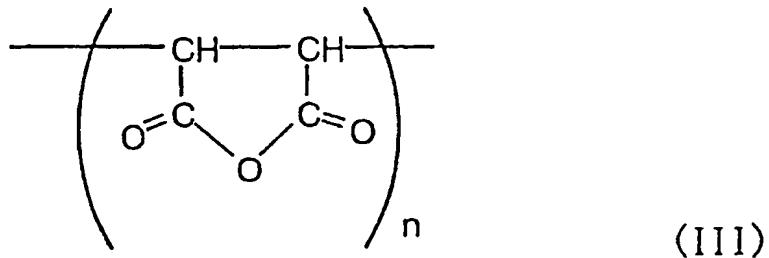
copolymer resin (2-1) comprising:

20 monomer unit (a) represented by formula (II):



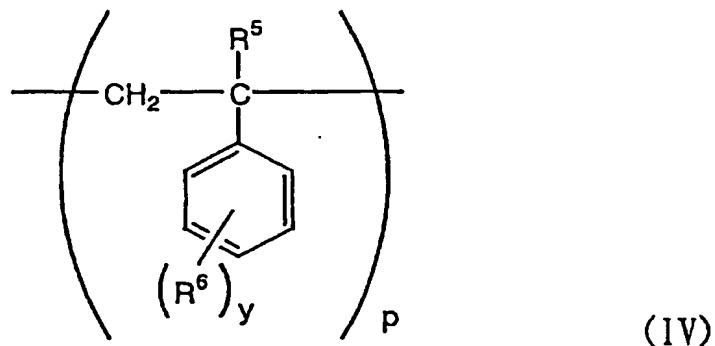
wherein R³ is a hydrogen atom, a halogen atom or a
 hydrocarbon group having 1 to 5 carbon atoms; R⁴'s are each
 independently a halogen atom, an aliphatic hydrocarbon
 25 group having 1 to 5 carbon atoms, an aromatic hydrocarbon
 group or a hydroxyl group; x is an integer of 0 to 3; and

m is a natural number representing the repeating number of a monomer unit in a copolymer, and monomer unit (b) represented by formula (III):

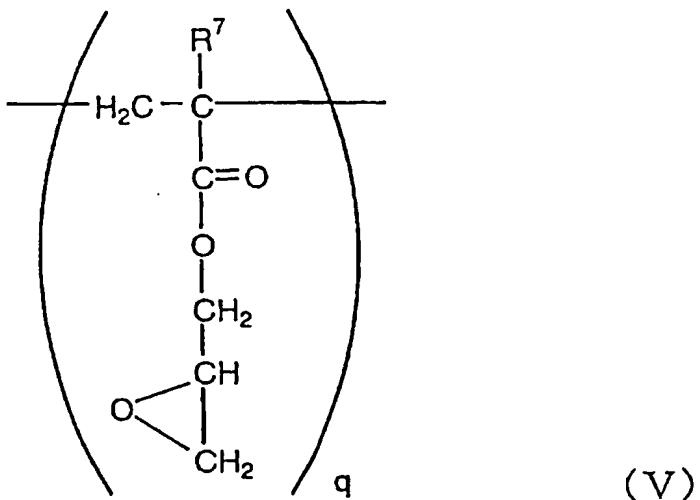


5 wherein n is a natural number representing the repeating number of a monomer unit in a copolymer; copolymer resin (2-2) comprising:

monomer unit (c) represented by formula (IV):



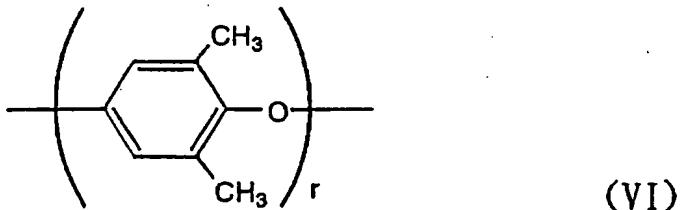
10 wherein R⁵ is a hydrogen atom, a halogen atom or a hydrocarbon group having 1 to 5 carbon atoms; R⁶'s are each independently a halogen atom, an aliphatic hydrocarbon group having 1 to 5 carbon atoms, an aromatic hydrocarbon group or a hydroxyl group; y is an integer of 0 to 3; and p is a natural number representing the repeating number 15 of a monomer unit in a copolymer, and monomer unit (d) represented by formula (V):



wherein R^7 is a hydrogen atom, a halogen atom or a hydrocarbon group having 1 to 5 carbon atoms; and q is a natural number representing the repeating number of a monomer unit in a copolymer; and

5 resin (2-3) comprising:

monomer unit (e) represented by formula (VI):

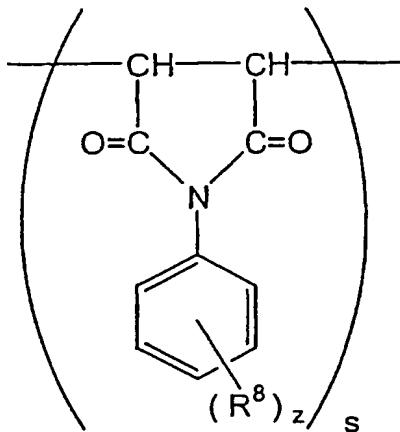


wherein r is a natural number representing the repeating number of a monomer unit in a copolymer.

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5. The thermosetting resin composition according to claim 4, wherein the copolymer resin (2-1) is a copolymer resin further comprising:

15 monomer unit (f) represented by the following formula (VII):



(VII)

wherein R⁸ is a halogen atom, an aliphatic hydrocarbon group having 1 to 5 carbon atoms, an aromatic hydrocarbon group, a hydroxyl group, a thiol group or a carboxyl group;
 5 z is an integer of 0 to 3; and s is a natural number representing the repeating number of a monomer unit in a copolymer.

6. The thermosetting resin composition according to any one of
 10 claims 1 to 5, which further comprises (4) an epoxy resin.

7. A prepreg using the thermosetting resin composition according to any one of claims 1 to 6.

15 8. A laminated board obtained by using and laminate molding the prepreg according to claim 7.

9. A thermosetting resin composition comprising a metal salt of a disubstituted phosphinic acid, wherein a dielectric constant
 20 of the composition is 3.0 or less at a frequency of 1 GHz or more.